Features

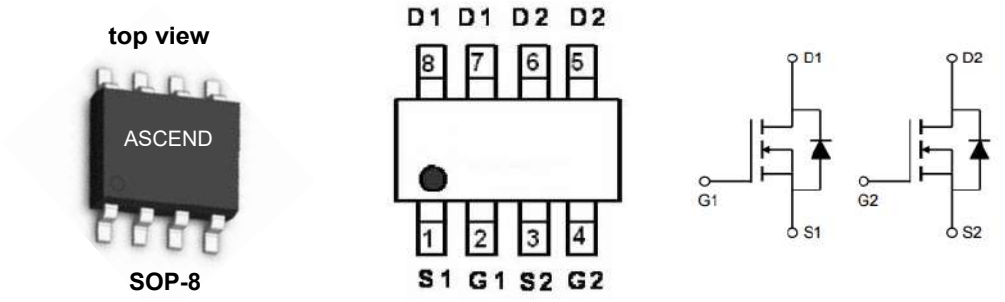
- Dual N-Channel,5V Logic Level Control
- Enhancement mode
- Fast Switching
- High Effective

Product Summary

V_{DS}	30	V
$R_{DS(on),max.}$@VGS=10V	20	mΩ
ID	9	A

Applications

- Power Management in Inverter System
- Synchronous Rectification



Maximum ratings, at T_j=25 °C, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		30	V
I_S	Diode continuous forward current	T_A =25°C	9	A
I_D	Continuous drain current @V_{GS}=10V	T_A =25°C	9	A
		T_A =70°C	5.0	A
I_{DM}	Pulse drain current tested ①	T_A =25°C	36	A
EAS	Avalanche energy, single pulsed ②		9	mJ
P_D	Maximum power dissipation	T_A =25°C	2.5	W
VGS	Gate-Source voltage		±20	V
MSL			Level 3	
T_{STG}	Storage temperature range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JL}$	Thermal Resistance-Junction to Lead	40	°C/W
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	50	°C/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	30	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=8A		15.5	20	mΩ
		V_{GS}=4.5V, I_D=6A		21.5	26	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	1.5	2.5	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=8A		15		S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=30V, V_{GS}=0V	-	-	10	uA
I_{GSS}	Gate-Source Leakage	V_{GS}=±12V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge	I_D=8A		4.1		nC
Q_{gs}	Gate-Source Charge	V_{DS}=15V	-	1.1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=4.5V	-	2.5	-	nC
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=15V	-	8	-	ns
t_r	Rise Time	I_D=1A	-	7	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=3.3Ω,V_{GS}=10V	-	15	-	ns
t_f	Fall Time	R_D=15Ω	-	5	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	344	-	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	48	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	38	-	pF
R_g	Gate Resistance	f=1.0MHz	-	5.6	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=1.1A, V_{GS}=0V	-	-	1.0	V
t_{rr}	Reverse Recovery Time	I_S= 8A, V_{GS}=0V,	-	15	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	14	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

3.Surface mounted on 1 in^2 copper pad of FR4 board, t ≤10sec ; 125 ℃/W when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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Typical Performance Characteristics

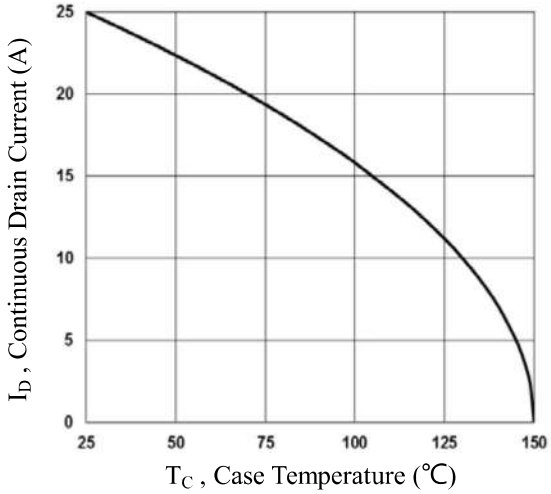


Fig.1 Continuous Drain Current vs. T_C

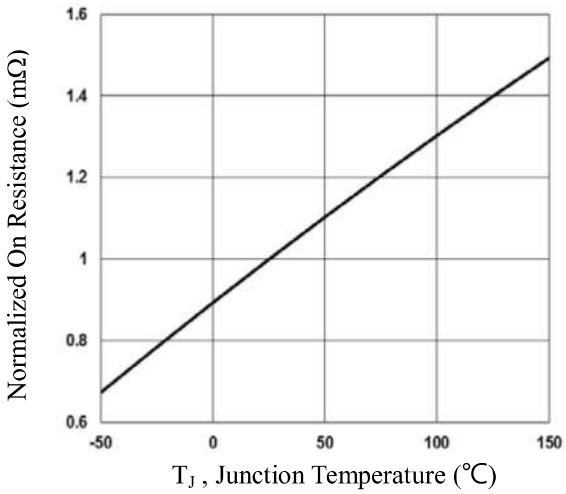


Fig.2 Normalized RDSON vs. T_J

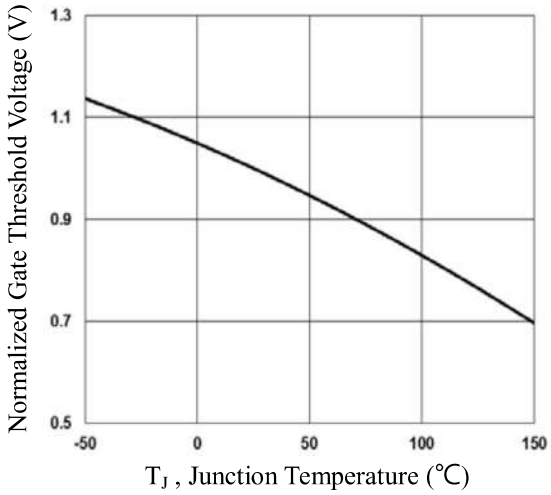


Fig.3 Normalized V_{th} vs. T_J

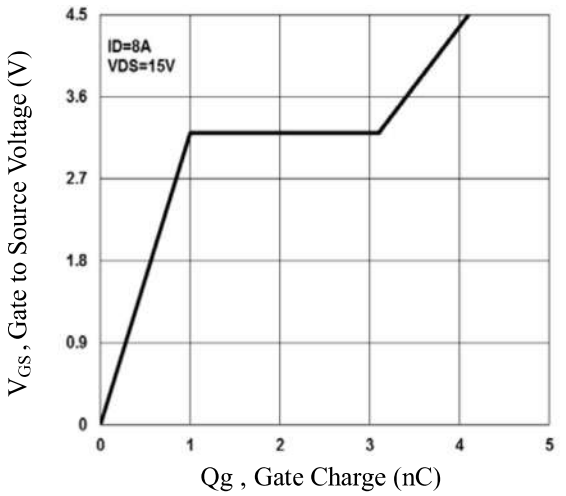


Fig.4 Gate Charge Waveform

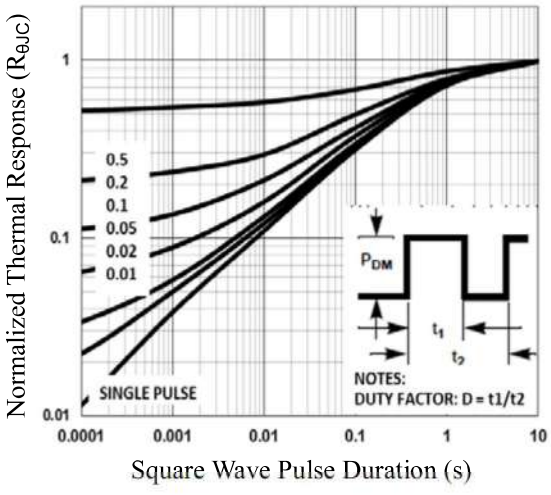


Fig.5 Normalized Transient Response

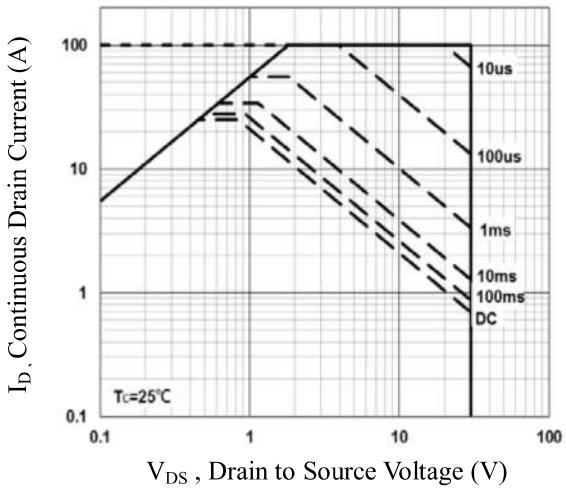


Fig.6 Maximum Safe Operation Area

Test Circuit

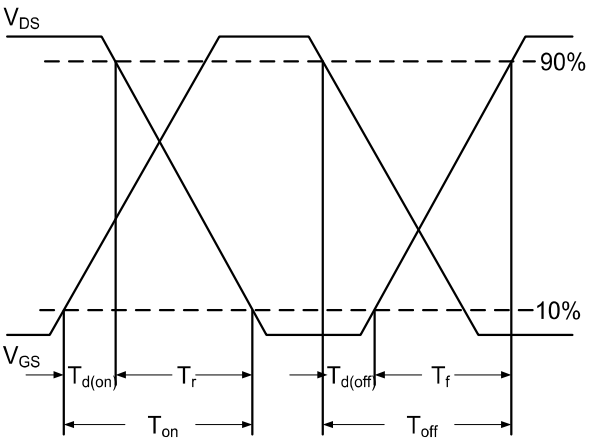


Fig.7 Switching Time Waveform

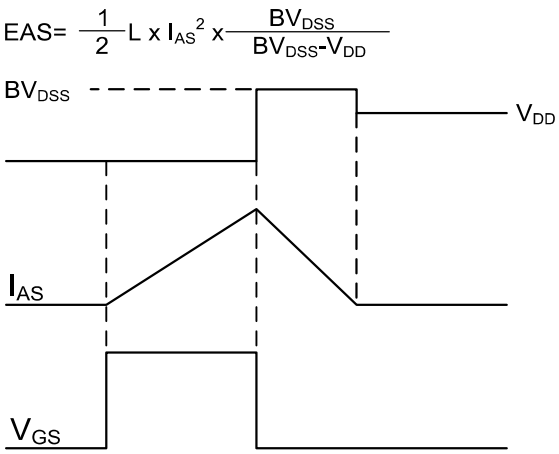
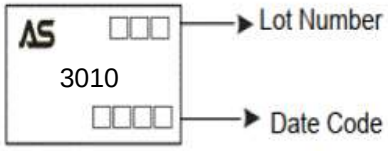


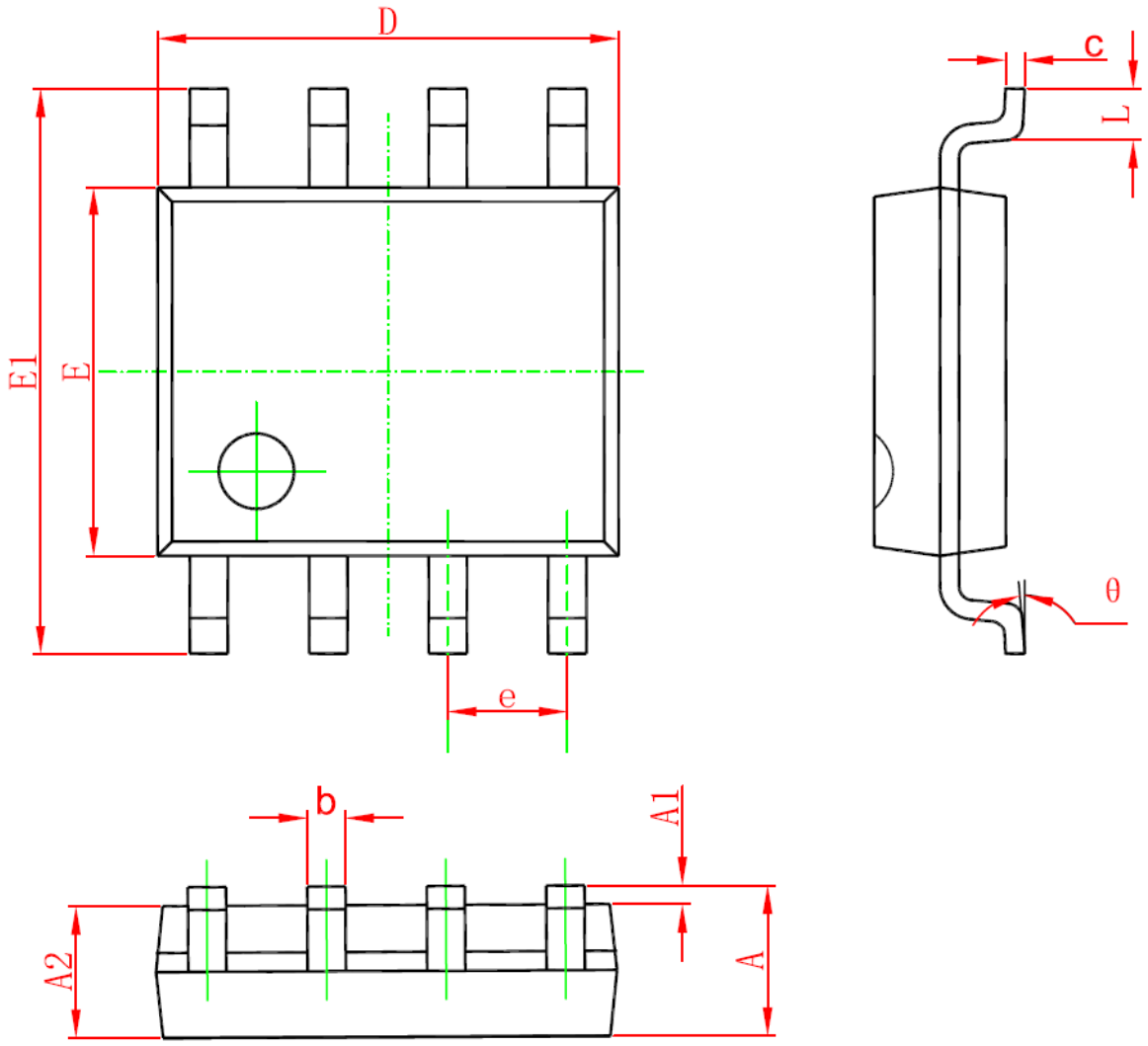
Fig.8 EAS Waveform

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM3010S-R	3010	SOP8	Tape&Reel	4000/Reel

PACKAGE	MARKING
SOP8	

SOP-8 PACKAGE IN FORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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